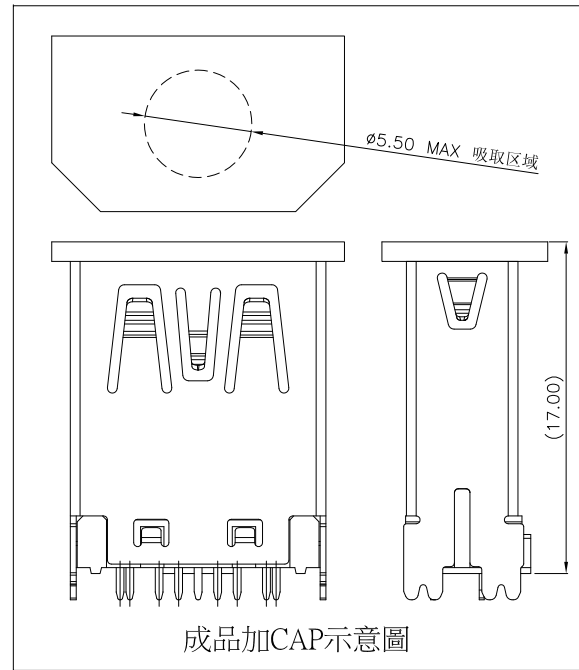
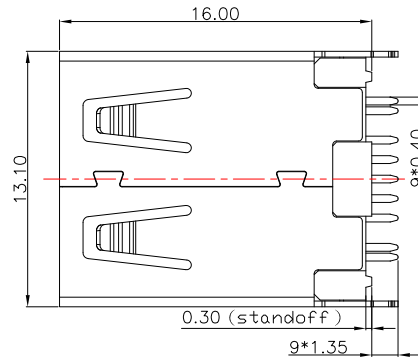


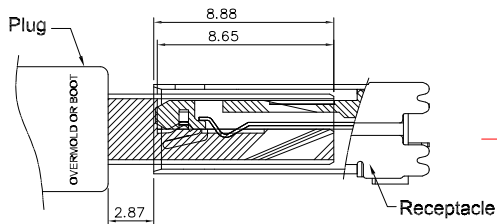
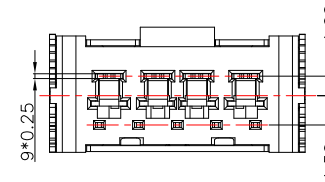
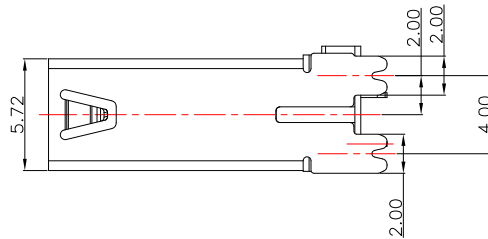
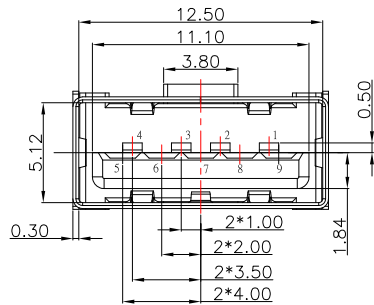
SUA-110V9-30x-S410

鍍層厚度:

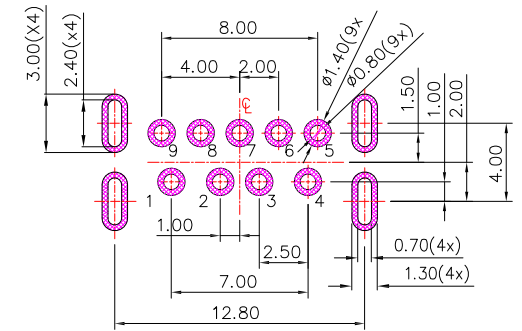
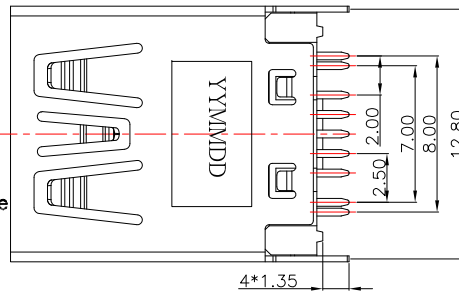
Blank : 1u"
2 : 15u"
3 : 30u"



成品加CAP示意圖



Mated Condition



RECOMMENDED PCB LAYOUT

NOTE:

1.MATERIAL:

1.1 Housing: LCP

1.2 Contact: Phosphor Bronze

1.3 Shell: SUS

2.Finish:

2.1 Contact: Plated Gold in Mating Area ;

Tin Plated on Solder Balls ;

Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

CONTACT

建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED:
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD. ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 09/14/22
DATE: 09/14/22
DATE: 09/14/22

MAT'L	TITLE	CONNECTOR
FINISH	MODLE	USB 3.0 AF 180度 H16.00 DIP 端子腳長1.35
SCALE	DWG NO.	SUA-110V9-30x-S410
SHEET NO.	PART NO.	SUA-110V9-30x-S410

ITEM NO.	DESCRIPTION	DRAWN	DATE
----------	-------------	-------	------